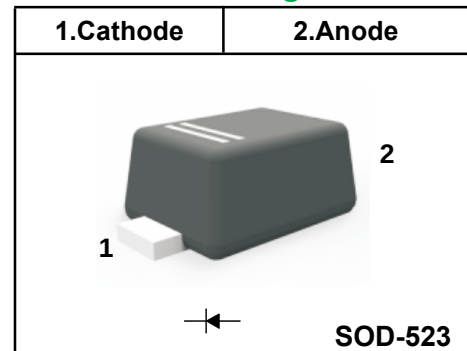


Silicon Epitaxial Planar Switching Diode

Pinning



Marking Code

BAS216WT	A
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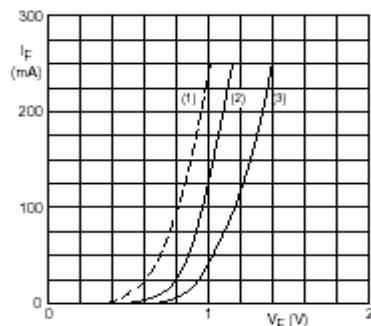
Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Value	Unit
Repetitive Peak Reverse Voltage	V_{RRM}	85	V
Reverse Voltage	V_R	75	V
Continuous Forward Current	I_F	250	mA
Repetitive Peak Forward Current	I_{FRM}	500	mA
Non-Repetitive Peak Forward Surge Current	I_{FSM}	at t=1μs	4
		at t=1ms	1
		at t=1s	0.5
Power Dissipation	P_{tot}	150	mW
Junction Temperature	T_J	150	°C
Storage Temperature Range	T_{STG}	- 65 to + 150	°C

Characteristics at Ta = 25°C

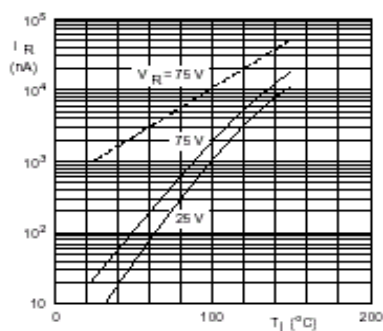
Parameter	Symbol	Max	Unit
Forward Voltage	V_F		mV
at $I_F = 1\text{ mA}$		715	
at $I_F = 10\text{ mA}$		855	
at $I_F = 50\text{ mA}$		1000	
at $I_F = 150\text{ mA}$		1250	
Reverse Current	I_R		nA μA μA μA
at $V_R = 25\text{ V}$		30	
at $V_R = 75\text{ V}$		1	
at $V_R = 25\text{ V}$, $T_J = 150^\circ\text{C}$		30	
at $V_R = 75\text{ V}$, $T_J = 150^\circ\text{C}$		50	
Diode Capacitance	C_{tot}		pF
at $V_R = 0\text{ V}$, $f = 1\text{ MHz}$		1.5	
Reverse Recovery Time	t_{rr}	4	ns
at $I_F = 10\text{ mA}$ to $I_R = 10\text{ mA}$, $I_R = 1\text{ mA}$, $R_L = 100\ \Omega$			

Characteristics at $T_a = 25\text{ }^{\circ}\text{C}$



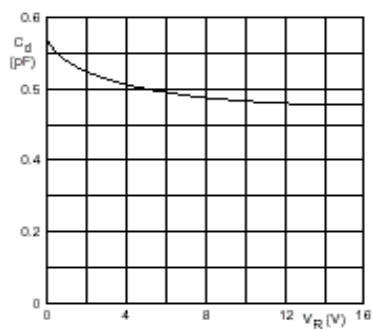
- (1) $T_J = 150\text{ }^{\circ}\text{C}$; typical values.
(2) $T_J = 25\text{ }^{\circ}\text{C}$; typical values.
(3) $T_J = 25\text{ }^{\circ}\text{C}$; maximum values.

Forward current as a function of forward voltage.



Dotted line: maximum values.
Solid line: typical values.

Reverse current as a function of junction temperature.



$f = 1\text{ MHz}$; $T_J = 25\text{ }^{\circ}\text{C}$.

Diode capacitance as a function of reverse voltage; typical values.

Ordering information

Package	Packing Description	Packing Quantity
SOD-523	Tape/Reel, 7" reel	3000PCS/Reel 120000PCS/Carton

Package Dimensions

SOD-523

Top view of the component. Dimensions shown: A (height), HE (total width), and C (thickness of the base). A note indicates "ALL ROUND" for the corners.

Side view of the component. Dimensions shown: A (height), E (width of the main body), and P (radius of the top edge).

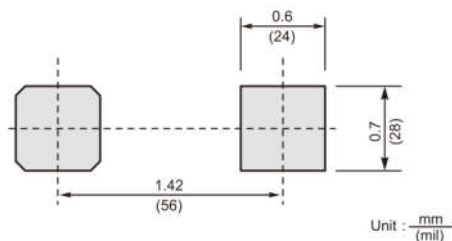
Front view of the component. Dimensions shown: D (width of the main body), E (height of the main body), e (height of the base), and L (width of the base).

Bottom view of the component. Dimension shown: N (width of the base).

底视图
bottom view

Dim.	Millimeter(mm)		mil	
	Min.	Max.	Min.	Max.
A	0.51	0.77	20	30
e	0.25	0.35	10	14
C	0.08	0.15	3	6
D	1.10	1.30	43	51
E	0.75	0.99	30	39
HE	1.50	1.70	59	67
N	0.35ref		14ref	
L	0.2ref		8ref	
P	R0.1 ALL ROUND		R4.0 ALL ROUND	
∠	10°			

The recommended mounting pad size



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